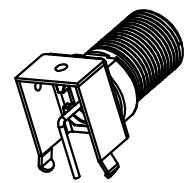
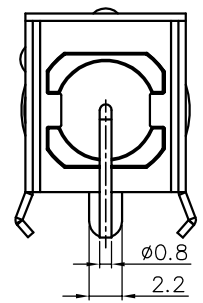
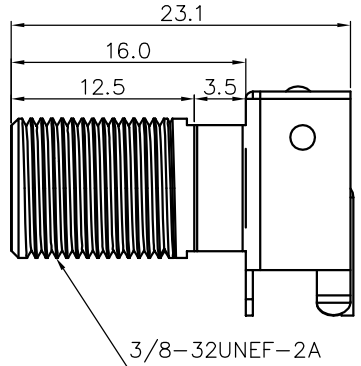
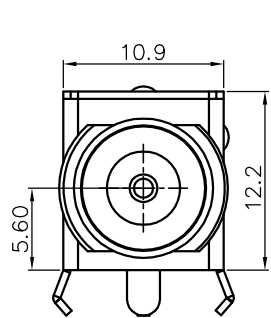


AUTOCAD GENERATED DRAWING. DON'T CHANGE BY HAND.

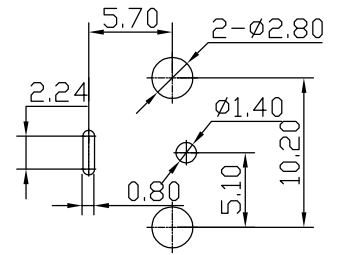
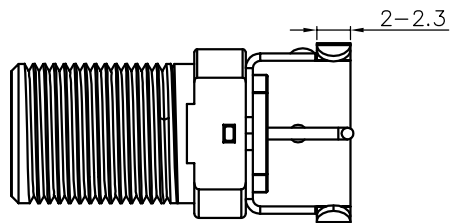
REV.	ECN. NO.	APPD.
A	BC-11-0086357	L.C. Wu
B	BC-14-0041764	Camvard



3D REVIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- INTERPRET DIMENSIONS PER ANSI/SCTE 02 2006;
- MATERIAL & FINISH:
  - BODY: ZINC ALLOY 3#(ASTM B86), NICKEL 80~120u' OVER Cu 300~350u' PLATING;
  - PIN: PURE COPPER T2, 50u' Ni UNDERPLATE WITH 120u' MIN. Tin TOP PLATE (MATTE Tin);
  - SOCKET: PHOSPHOR BRONZE, 50u' Ni UNDERPLATE WITH 120u' MIN. Tin TOP PLATE(MATTE Tin);
  - FRAME: TINPLATE(JIS G3303 SPT #50), THCKNESS=0.5mm, DEGREASE, OR SPECIAL REQUIREMENT;
  - INSULATOR: PPS OR HTN; FLAMMABILITY -UL94V-0; 260°C FOR MINIMUM 5S;
- ELECTRICAL:
  - 3.1 IMPEDANCE: 75Ω;
  - 3.2 RETURN LOSS: <-14dB @ 5MHz~1GHz;
  - 3.3 INSERTION LOSS: -0.3dB @ 5MHz~1GHz;
  - 3.4 CENTER RESISTANCE: 10mΩ MAX.;
  - 3.5 OUTER RESISTANCE: 5mΩ MAX.;
  - 3.6 DIELECTRIC WITHSTANDING VOLTAGE 750V (AC);
- THE F-CONNECTOR SHALL COMPLY WITH SHIELDING HOLE: TORQUE STRENGTH: 30 IN-lbs;
- CENTRICITY OF THE SOCKET SHALL BE ±0.1;
- TEMPERATURE RANGE: -40°C TO +85°C;
- COMPLIANCE ROHS.



RECOMMENDED PCB LAYOUT(TOP VIEW)

X.± 0.30	X'± 5'	UNITS MM	NAME(INTENDED USE)	<b>FOXCONN®</b> FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X± 0.25	.X'±	MAT'L	CUSTOMER DRAWING	
.XX± 0.20	.XX'±	FINISH	PART NO.(INTENDED USE)	CLASS: <input type="checkbox"/> CONFIDENTIAL <input type="checkbox"/> SECRET <input checked="" type="checkbox"/> GENERAL
XXX±	.XXX'±		KFA4110-N007-4F	APPD: Camvard 08/19'14
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF FOXCONN INTERCONNECT TECHNOLOGY LIMITED.			Q'TY	DWG NO.: 389-0000-381
			CHKD: Z.H Xu 08/19'14	SCALE SHEET REV.
			DR: Wu Chen 08/19'14	1:1 1/1 B